ASSOCIATION CONN ELECTRONICS INDU	Material Composi © Copyright 2005. IPC, international and Pan-Ar	Bannockb	urn, Illinois. A	Il rights reserved untions.	nder both	This docume level parts, t	ent is a declarat he declaration e	on of the substancompasses all	ances within the lower level ma	e manufacture terials for wh	er listed iten hich the man	n. Note: if ufacturer	the item is an as has engineering	sembly with low responsibility.
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				eous Materia	als and Mfg Information				
Supplier Info	formation													
Company name*			Company unique ID			1	Unique ID Authority				Response Date*			
nsemi											2024-05-16			
ontact Name			Title - Contact			1	Phone - Contact*				Email - Contact*			
Product-Env-S	Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Authorized Representative*			Title - Representative]	Phone - Representative*				Email - Representative*			
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Requ	Requester Item Number Mfr Iten		n Number Mfr Item Name				Effective Date	Version	ersion Manufacturing Site		We	ight*	UOM	Unit Type
	FSFR1800XS Hig		High Pwr FPS for HB		2024-05-16		СРА	СРА		9.548	mg	Each		
Ianufacturi	ing Proccess Information	n												
Terminal Plating / Grid Array Material		ial To	Ferminal Base Alloy J-STD-020 MS		L Rating	Peak Process Body Temperate		erature Max T	ure Max Time at Peak Temp		Numbe	er of Reflow Cyc	les	
Matte Tin (Sn) - annealed		С	CU Alloy NA			0 C		30	30 seco		3			
omments														
or more inform	mation regarding material con	nposition p	please refer to	o page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et						
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in ifies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted					
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the					
Supplier Digital Signature	astislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

sigma range of distribution unless otherwise noted).									
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure	
Die	9.87	mg	Supplier	Silicon (Si)	7440-21-3		9.87	mg	
Die Attach	2.18	mg	Supplier	Silver (Ag)	7440-22-4		0.0327	mg	
			А	Lead (Pb)	7439-92-1	7a	2.0383	mg	
			Supplier	Tin (Sn)	7440-31-5		0.109	mg	
Lead Frame	339.343	mg	Supplier	Zinc (Zn)	7440-66-6		0.407	mg	
			Supplier	Iron (Fe)	7439-89-6		7.805	mg	
			Supplier	Copper (Cu)	7440-50-8		331.0291	mg	
			Supplier	Phosphorus (P)	7723-14-0		0.1019	mg	
Mold Compound-Black	693.0	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		34.65	mg	
			Supplier	Carbon Black (C)	1333-86-4		6.93	mg	
			Supplier	Fused Silica (SiO2)	60676-86-0		616.77	mg	
			Supplier	Phenolic Resin (Novolac)	9003-35-4		34.6499	mg	
Plating	4.92	mg	Supplier	Tin (Sn)	7440-31-5		4.92	mg	
Wire Bond - Cu	0.235	mg	Supplier	Copper (Cu)	7440-50-8		0.235	mg	

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3